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(54) **HEATER FOR SEMICONDUCTOR MANUFACTURING APPARATUS**

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(**) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(52) **U.S. Cl.**

USPC **D13/182**

(58) **Field of Classification Search**

USPC D7/407, 408; D13/102, 103, 110, 118, D13/123, 154, 156, 173, 184, 199; D14/230, 233; D15/140; D23/314, 386, D23/415, 417–419, 499

CPC H01L 21/00; H01L 21/67; H05B 1/02; H05B 3/26; H05B 3/44; F27D 11/00; C23C 16/45; C23C 16/46; C23C 16/52

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a heater for semiconductor manufacturing apparatus, as illustrated and described.

DESCRIPTION

FIG. **1** is a top plan view of a heater for semiconductor manufacturing apparatus according to our new design;
FIG. **2** is a bottom plan view thereof;
FIG. **3** is a front view thereof;
FIG. **4** is a back view thereof;
FIG. **5** is a left side view thereof; and,
FIG. **6** is a right side view thereof.

1 Claim, 5 Drawing Sheets

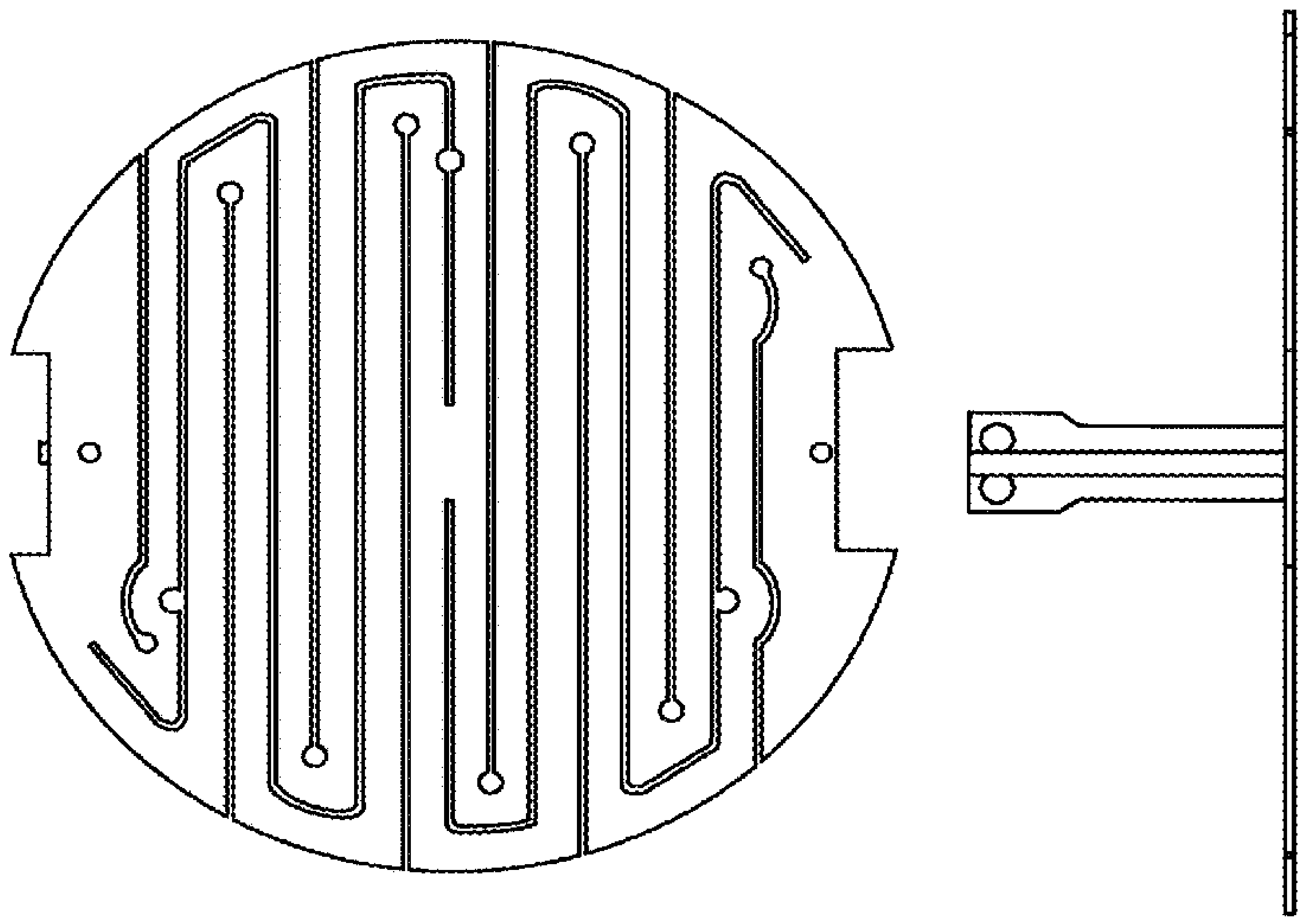

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FIG. 1

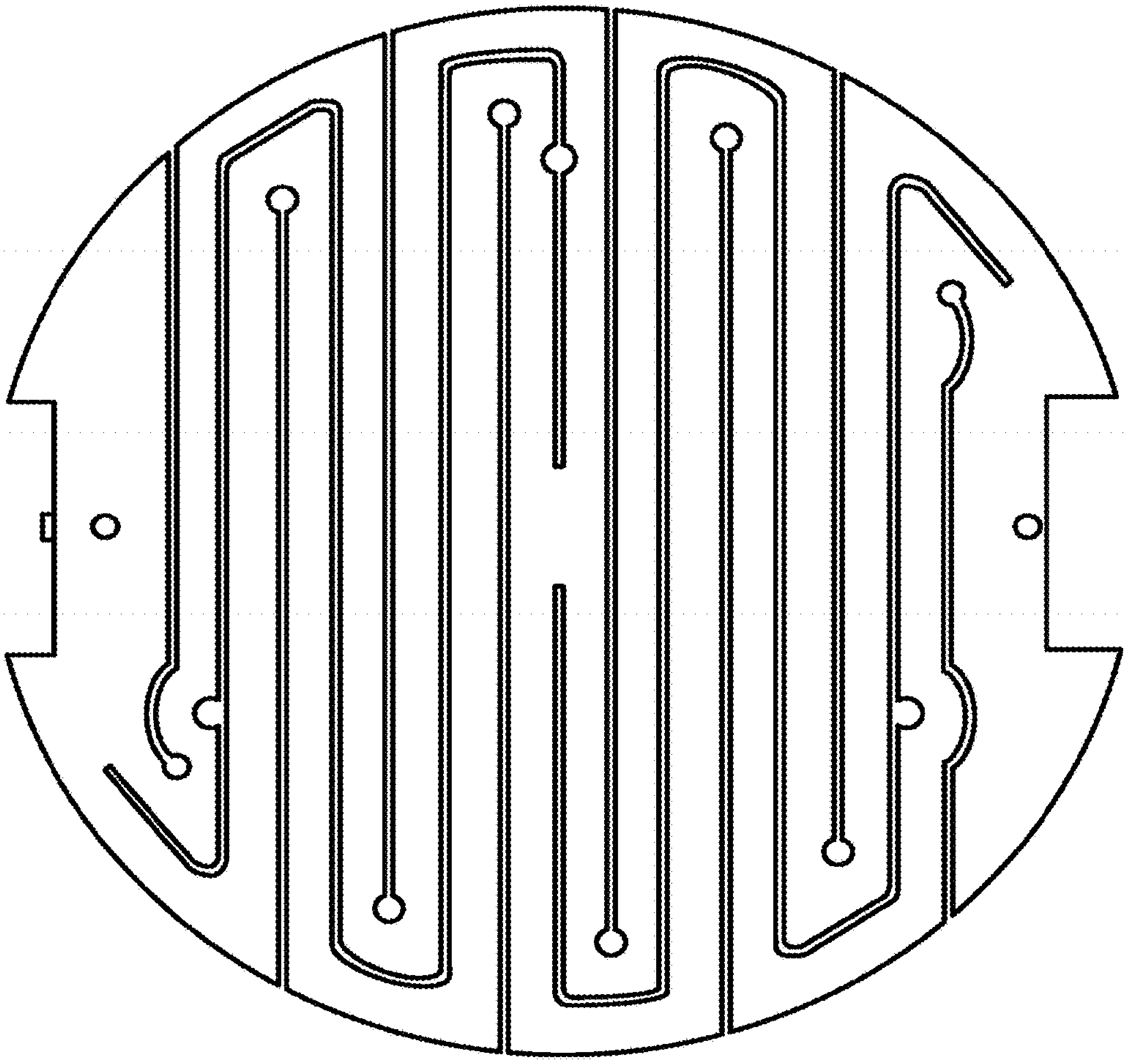

FIG.2

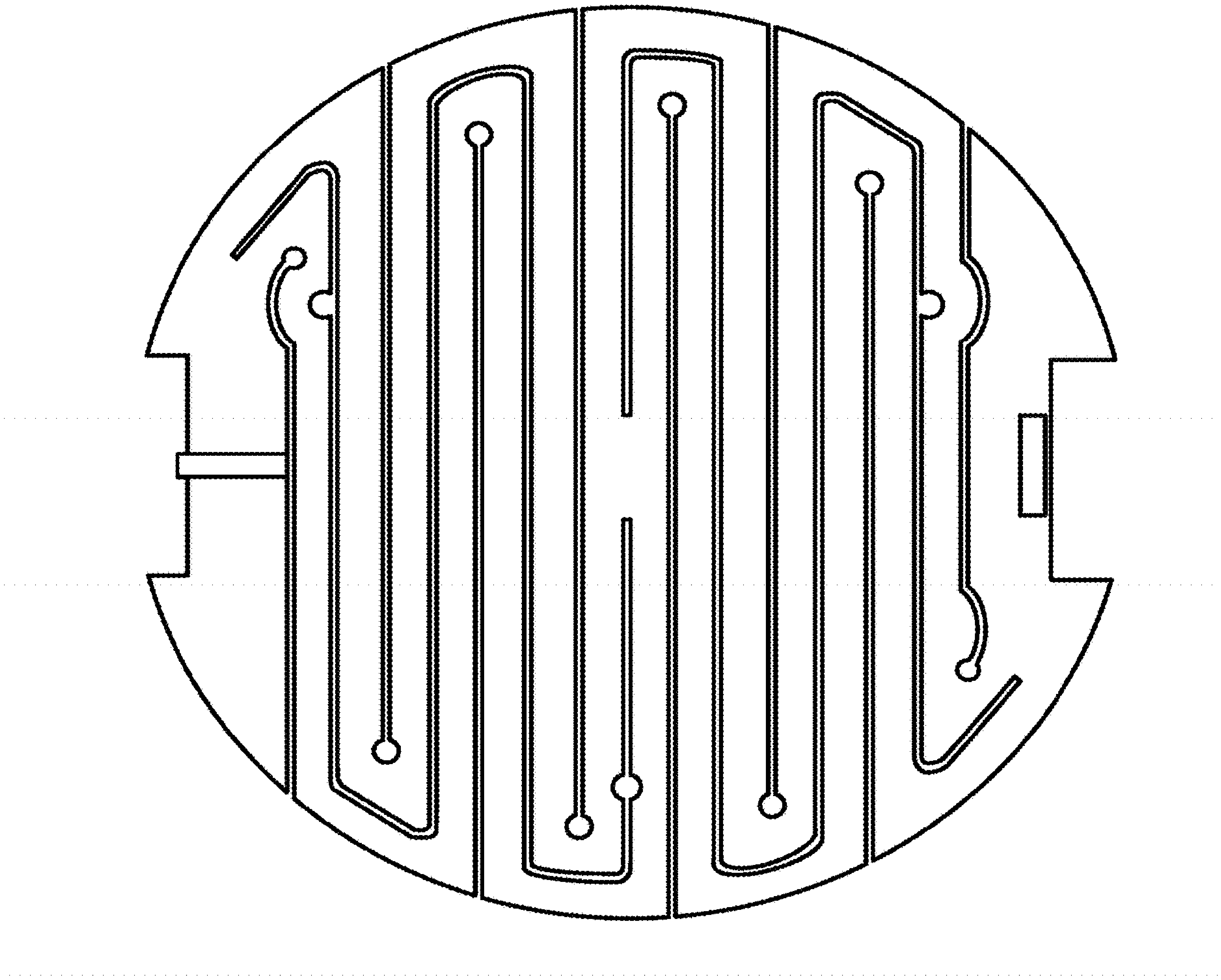

FIG.3

FIG.4

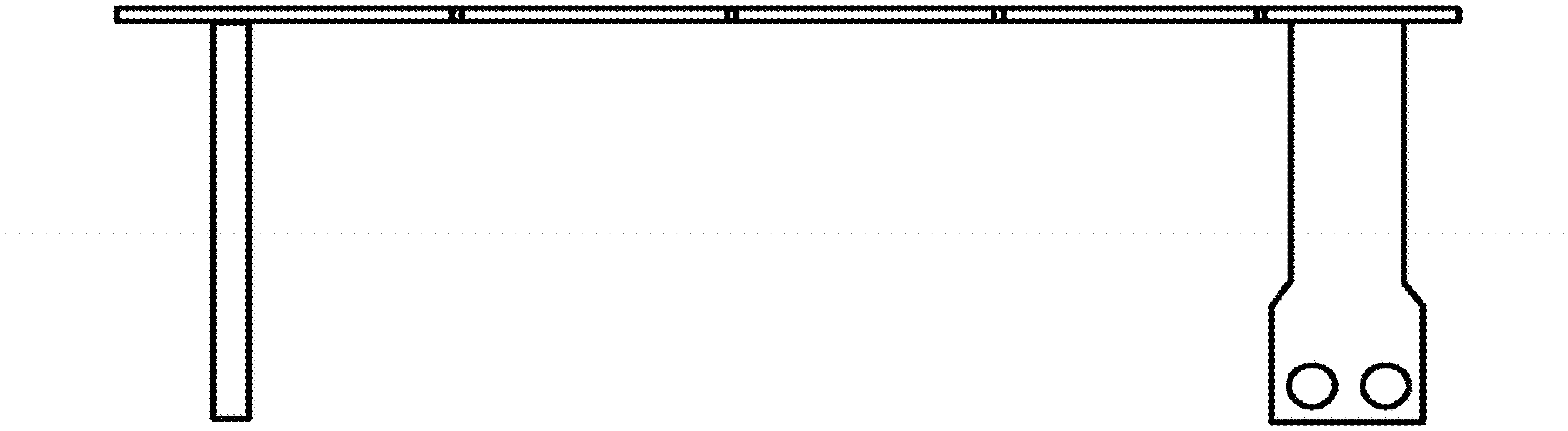

FIG.5

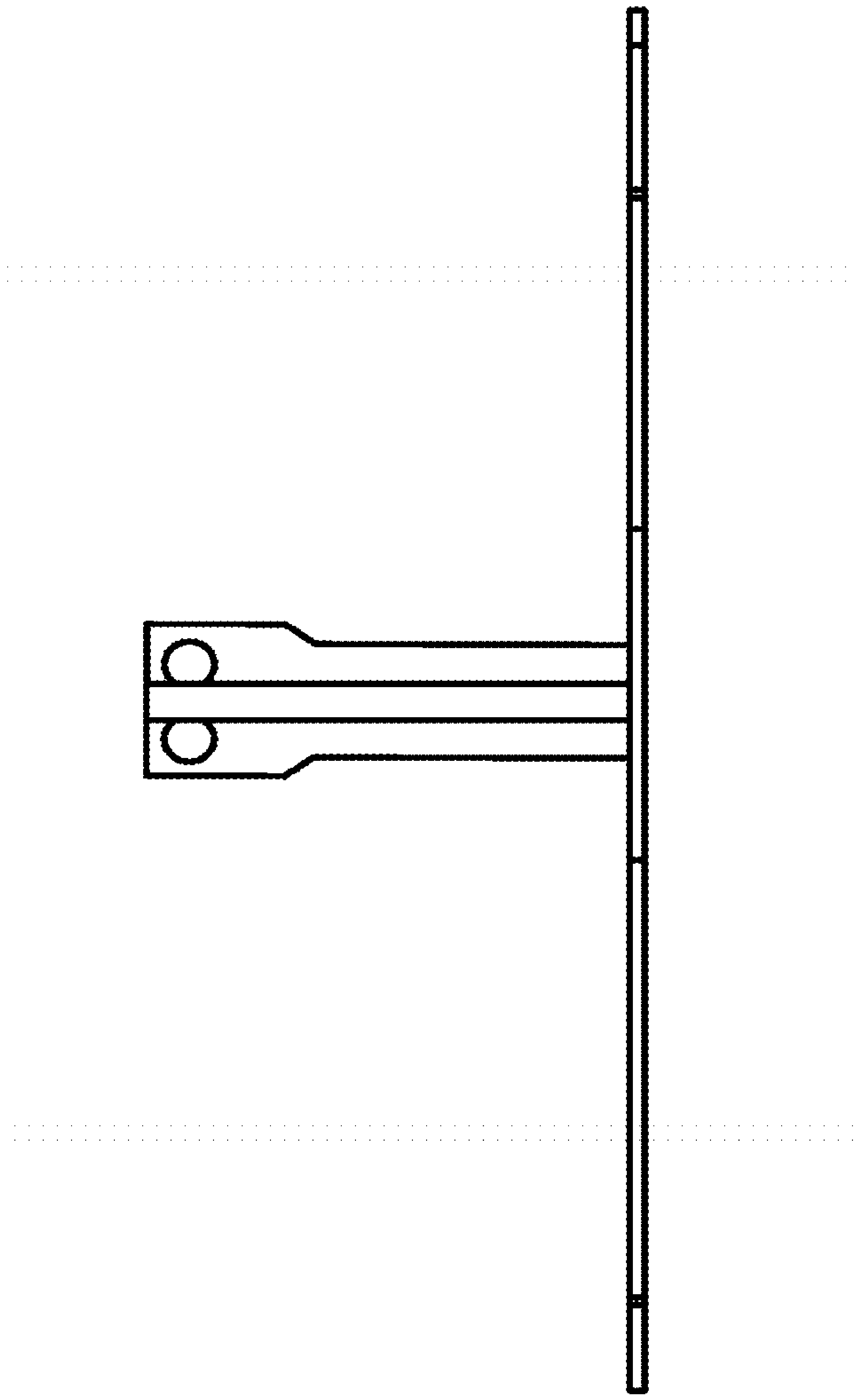

FIG. 6